

DIODE ARRAYS

Features

These products are designed for data line protection at the P.C. board level as well as for other applications including: cameras, smart cards, etc. which require multiple protection with limited board space.

- 300 TO 600 WATTS PEAK PULSE POWER
- DATA AND BUS LINE APPLICATIONS
- CONVENTIONAL THRU-HOLE OR SURFACE MOUNTABLE PIN CONFIGURATIONS
- LOW CAPACITANCE AVAILABLE
- 8 PIN TO 28 PIN VERSATILE PACKAGES
- COMMON GROUND OR INDEPENDENT DIODE POSITIONS AVAILABLE
- UNIDIRECTIONAL OR BIDIRECTIONAL CAPABILITIES
- VOLTAGE RANGE OF 5 VOLTS TO 200 VOLTS AVAILABLE

Maximum Ratings

- Peak Pulse Power 8/20 μ s = up to 600 Watts.
- Operating and Storage Temperature Range = -55° to +150°C
- Repetition Rated (duty cycle) = 0.01%

Mechanical Characteristics

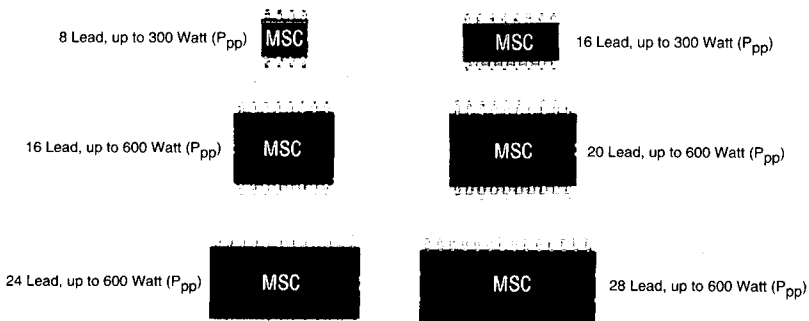
CASE: Molded or Ceramic Options.

TERMINAL: Lead/Tin Plated or Solder Dipped.

MARKING: Body Marked With Dot On Top For Pin No. 1 Location.

PACKAGE DIMENSIONS: Per Industry Standard PDIP's, CERDIPs, SOICs, and PLCCs. Consult Factory For Further Details.

The illustrations below demonstrate SOIC surface mount options. Note: P_{pp} @ 8 x 20 μ s.



MICROSEMI CORP.- SCOTTSDALE OFFERS THE FOLLOWING THREE HI-REL (MILITARY) PROCESSING LEVELS FOR MODULE PRODUCTS.

HI-REL (MILITARY) MODULE PROCESSING

Processing Level Code

H1
H2
H3

Testing Provided

Sub-module screening
Sub-module & module screening
Sub-module & module screening
& Group B and C lot testing

Sub-Module Screening Test Procedure (100%)

Storage
Temperature Cycle
Acceleration
Fine & Gross Leak
Electrical #1, Read & Record
Surge
Electrical #2, IR (go no go)
H.T.R.B. (96 hours)
Electrical #3, Read & Record
Compute Delta (Δ) parameters
Group A

Module Screening Test Procedure (100%)

Storage
Temperature Cycle
Electrical #1, Read & Record
Surge
Electrical #2, IR (go no go)
H.T.R.B. (96 hours)
Electrical #3, Read & Record
Compute delta (Δ) parameters
Marking
Group A

MODULE ASSEMBLY GROUP B AND C TESTING

Module Assembly Group B Testing (Sample)

- Sub-Group 1
- Solderability
 - Resistance to solvents
- Sub-Group 2
- Temperature Cycle
- Sub-Group 3
- Operating Life

Module Assembly Group C Testing (Sample)

- Sub-Group 1
- Physical Dimensions
- Sub-Group 2
- Terminal Strength
 - Moisture Resistance
- Sub-Group 3
- Shock & Vibration
- Sub-Group 4
- Salt Atmosphere
- Sub-Group 5
- Operating Life

NOTE: To order modules with this additional screening, add the corresponding processing level code as a suffix to the standard part number. Consult factory for additional information.

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The diode experts

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